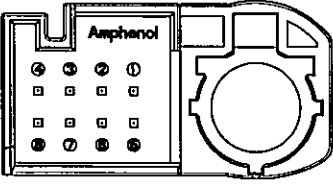
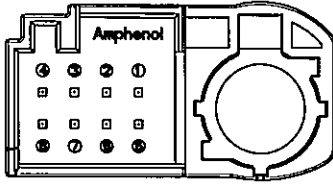
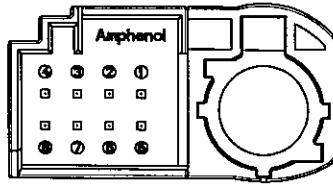
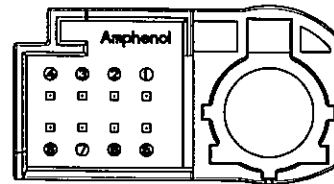
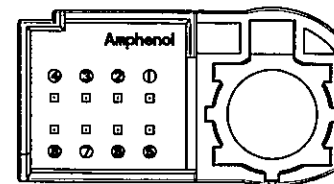


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REVISIONS				
SYM	ECN	DESCRIPTION	DATE	APPROVED
-	----	SEE SHEET 1/2	----	---

Table 1
keys and colors

				
Coding A graphite black sim. RAL9011	Coding B natural sim. RAL9001	Coding C light blue sim. RAL5012	Coding D claret violet sim. RAL4004	Coding Z water blue sim. RAL5021

Notes:

1. Material and plating:

Component	Material	Plating
Housing:	PA4T, UL94-V0, color see table1	
Dielectric:	LCP, UL94-V0, color black	
Outer contact (PCB):	Zinc alloy	Tin, 2-6um, over nickel
Cover:	Stainless Steel.	
HSD contact:	Copper alloy	Gold, 0.15um (interface); gold flash(PCB)
MQS contact:	Copper alloy	Tin, 2-6um, over nickel

4. Environmental data:

Temperature range	-40°C to +105°C
Thermal shock	DIN IEC 60068-2-14 Test Na
Temperature and humidity	USCar 2 - 4 5.6.2
Vibration (Random)	DIN IEC 60068-2-64
Mechanical Shock	DIN IEC 60068-2-27
High-Temp. Exposure	DIN IEC 60068-2-2
Soldering profile	acc. to IEC 60068-2-58; Group 3&4
2011/65/EU (RoHS)	compliant

2. Electrical data, HSD side:

Impedance, even mode	≈ 32 Ω common mode only
Impedance, differential mode	100 Ω differential signaling, for one pair or quad cable shielded
Frequency	DC to 2.0 GHz
Return loss	≥ 20 dB to 1.0 GHz
	≥ 17 dB to 2.0 GHz
Insertion loss	≤ 0.1 dB @ 1.0 GHz
Skew (between signal contacts)	≤ 20 psec. (can be reduced by layout)
Nearend-Crosstalk	≤ 30 dB
Farend-Crosstalk	≤ 35 dB
Insulation resistance	≥ 1x10 ³ MΩ
Signal contact resistance	≤ 10 mΩ
Outer contact resistance	≤ 7.5 mΩ
Test voltage	500 V rms
Working voltage	100 V rms
Test current capability at 80°C	≤ 1.5 A DC
Test current capability at 80°C MQS pins	≤ 5.0 A DC (dependent on mating connector and cable)

5. Packing

Standard	100 pcs in tape & reel
Weight	12.97 g/pc

6. Order P/N system:

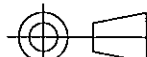
HSD NXRP PCB 8X

Coding: _____
See table 1

Packing method:
A- Packing by tape & reel
B- Packing by tray
C- Single Packing

3. Mechanical data, HSD side:

Mating cycles	≥ 25
Engagement force each contact	≤ 30 N
Disengagement force each contact	≥ 5 N
Retention force latch	≥ 110 N
Coding efficiency	≥ 80 N

UNLESS OTHERWISE SPECIFIED TOLERANCES U.S. METRIC .X +/- 0.50 .XX +/- 0.25 .XXX +/- 0.10 FRACTIONS +/- 1/16 ANGLES +/- 5° FOR MATERIALS AND FINISHES SEE NOTES REMOVE SHARP EDGES DIMENSIONS U.S. INCHES METRIC MM	APPROVAL DRAWN Kaka Yang CHECKED <i>[Signature]</i> CHECKED <i>[Signature]</i>	DATE 11/21/16 11/21/16	Amphenol TITLE HSD + 8pos MQS R/A plug connector NORTH LOCATION SIZE DRAWING NO. A4 HSD NXRP PCB 8X SCALE 2:1 SHEET 2 OF 2
	ANGLE OF PROJECTION 	DRAWING FILE: H:\PCB\HSD\HSD_NXRP_PCB_8X.dwg	